EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	852	(iron near2 nickel near2 alloy) near5 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L2	4647	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L3	1526	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L4	564	257/752.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L5	1079	257/760.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L6	326	257/792.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L7	2901	257/773.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L8	878	257/e21.122.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01

L9	46	257/e21.128.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L10	852	(iron near2 nickel near2 alloy) near5 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L11	4647	257/758.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L12	1526	257/750.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L13	564	257/752.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L14	1079	257/760.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L15	326	257/792.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L16	2901	257/773.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L17	878	257/e21.122.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01

L18	46	257/e21.128.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:01
L19	69	(yoji near2 asahi). inv. or (yukiji near2 ootsuka). inv. or (keisuke near2 ueda).inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:03
L20	1	l10 and l19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:04
L21	942	(substrate and interconnect$3 near2 pattern and (resin or insulat$3 or dielectric)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:06
L22	942	(substrate and (interconnect$3 near2 pattern) and (resin or insulat$3 or dielectric)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:07
L23	212	(substrate and (interconnect$3 near2 pattern) and (resin or insulat$3 or dielectric) and chip).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:07
L24	229	(substrate and (interconnect$3 near2 pattern) and (resin or insulat$3 or dielectric) and (die or chip)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/11 18:07

9/11/08 6:08:14 PM
C:\Documents and Settings\vtrinh\My Documents\EAST\workspaces\10827318.wsp